



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-10-17
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Material Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MHO7*TAW6V5B	A	BO2A	2013-10-17
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9 - 3.9 - 1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC. Valid for CP: ITA6V5B1RL,ITA6V5B1.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MH07*TAW6V5B		80			
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.443	mg	supplier	die	Silicon (Si)	7440-21-3		3.322	mg	964856	41525
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.048	mg	13941	600
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.017	mg	4938	213
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.022	mg	6390	275
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	581	25
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1743	75
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.026	mg	7552	325
Leadframe	Copper & its alloys	34.925	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.705	mg	965068	421313
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.793	mg	22706	9913
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	1374	600
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.042	mg	1203	525
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.313	mg	8962	3913
Leadframe				supplier	metallization	Palladium (Pd)	7439-89-6		0.013	mg	372	163
Leadframe				supplier	metallization	Gold (Au)	12185-10-3		0.011	mg	315	138
Die attach	Other Organic materials	0.714	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.649	mg	908964	8113
Die attach				supplier	glue or tape	acrylate	proprietary		0.036	mg	50420	450
Die attach				supplier	glue or tape	Methacrylate	proprietary		0.029	mg	40616	363
Bonding wire	Other inorganic materials	0.037	mg	supplier	wire	Copper (Cu)	7440-50-8		0.037	mg	1000000	463
encapsulation	Other Organic materials	40.881	mg	supplier	mold compound	Epoxy Resin	proprietary		3.066	mg	74998	38325
encapsulation				supplier	mold compound	Phenol Resin	proprietary		2.044	mg	49999	25550
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		35.404	mg	866026	442550
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.204	mg	4990	2550
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.163	mg	3987	2038